

This specification applies to the SLO160808T Series of wire wound SMD power inductor.

#### 2. Product Description and Identification (Part Number)

1) Description:

SLO160808T series of Wire wound SMD power inductor.

2) Product Identification (Part Number)

SLO	160808	Т	1R0	М	Т	Т
(1)	(2)	(3)	(4)	(5)	(6)	(7)

- (1) Series Type
- (2) Dimension: LxWxH
- (3) Material Code
- (4) Inductance:R68=0.68uH;1R0=1.0µH
- (5) Inductance Tolerance: $M=\pm 20\%, N=\pm 30\%$
- (6) Company Code
- (7) Packaging: packed in embossed carrier tape

#### 3. Electrical Characteristics

Please refer to Item 5.

- 1) Operating temperature range (individual chip without packing):  $-40^{\circ}$ C ~  $+125^{\circ}$ C (Including Self-heating).
- 2) Storage temperature range (packaging conditions): -10 $^{\circ}$ C ~ +40 $^{\circ}$ C and RH 70% (Max.).

#### 4. Shape and Dimensions (Unit:mm)

Dimensions and recommended PCB pattern for reflow soldering, please see Fig4-1 and Table4-1

## Shape and Dimensions:

### **Recommended pad:**



Fig4-1

## Table 4-1

A	L	В	С	D	а	b	С
1.6±	0.2	0.8±0.2	0.90Max	0.50±0.2	0.70 Ref	0.55 Ref	1.0 Ref



#### 5. Electrical Characteristics

Part Number	Inductance	DC Resistance		Saturation Current		Heat Rating Current	
	1MHz/1V	Max.	Тур.	Max.	Тур.	Min.	Тур.
Units	uH	Ω	Ω	A	А	A	А
Symbol	L	DCR		Isat		Irms	
SLO160808T1R0MTT	1.0±20%	0.140	0.115	2.0	2.3	1.3	1.6
SLO160808T2R2MTT	2.2±20%	0.300	0.250	1.2	1.4	0.9	1.0

Note: %1: Rated current: Isat(max.)or Irms(max.), whichever is smaller;

※2: Saturation Current: Max. Value, DC current at which the inductance drops less than 30% from its value without current; Typ. Value, DC current at which the inductance drops 30% from its value without current;

3: Irms: DC current that causes the temperature rise ( T) from 20°C ambient.

For Max. Value,  $\triangle T \le 40^{\circ}$ C; for Typ. Value,  $\triangle T$  is approximate  $40^{\circ}$ C.

The part temperature (ambient + temp. rise) should not exceed  $125^{\circ}$ C under worst case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

%4:Absolute maximum voltage:DC 20V

#### 6. Structure

The structure of SLO160808T product.



NO.	Components	Material
1	Core	Soft magnetic Metal
2	Wire	Polyurethane system enameled copper wire
3-1	Flootradoa	Inside Cu
3-2	Electrodes	Ni+Sn Plating Chemicals



△f: Clearance between terminal and the surface of plate must be 0.12mm max when coil is placed on a flat plate.



# 7. Reliability Test

Items	Requirements	Test Methods and Remarks			
7.1 Bonding Strength		It shall be soldered on the substrate. Applying Force(F): 10N Hold Duration: 5s			
7.2	Chip coil shall not be damaged	Substrate: Glass-epoxy substrate			
Bending		(100×40×1.0mm)			
ouchgui		Speed of Applying Force: 0.5mm / s			
		Deflection: 2mm			
		Hold Duration: 20s Pressing device ↓ □加圧治具 R340 ▲ 訪料 □ Specimen 45 <sup>62</sup> 45 <sup>62</sup>			
7.3	No visible mechanical damage.	1) Solder the inductor to the testing jig (glass epoxy			
Vibration	Inductance change: Within $\pm 10\%$	board) using eutectic solder.			
	Cu pad Solder mask	<ul> <li>a) The inductor shall be subjected to a simple naminic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz.</li> <li>3) The frequency range from 10 to 55Hz and return to 10Hz shall be traversed in approximately 1 minute. this motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours).</li> </ul>			
7.4	The wetting area of the electrode shall	Flux:Ethanol solution of rosin,25(wt)%			
Solderability	be at least 90% covered with new	Solder : Sn-3.0Ag-0.5Cu			
	solder coating.	Pre-Heating:150±10°C / 60 to 90s			
		Solder Temperature:245±5°C			
		Immersion Time:3 s			
7.5	Appearance:No damage	Reflow soldering method			
Resistance to	Inductance Change : within ±10%	Flux: Ethanol solution of rosin,25(wt)%			
Soldering		Solder: Sn-3.0Ag-0.5Cu			
Heat		Pre-Heating: 150 to 180°C / 60 to 120s			
		Solder Temperature: 230°C min. / 20 to 40s			
		Peak Temperature: 250+5/-0°C			
		Reflow times: 2 times max			
		Test board shall be 0.8 mm thick. Base material shall			
		be glass epoxy resin.			
		Then measured after exposure Standard atmospheric conditions for 1~2h.			



## 7. Reliability Test

Items	Requirements	Test Methods and Remarks		
7.6		Temperature: 125±2°C		
Heat		Time: 500h (±12h)		
Resistance		Then measured after exposure Standard atmospheric		
		conditions for 1~2h.		
77	-	Tomporatura: 40+2°C		
Cold		Time: $500h(\pm 12h)$		
Resistance		Time: Soon $(\pm 12n)$		
		Then measured after exposure Standard atmospheric		
	Appearance:No damage	conditions for 1~2h.		
7.8	Inductance Change : within +10%	Temperature: 40±2°C		
Humidity		Humidity: 90 to 95%(RH)		
		Time: 500h (±12h)		
		Then measured after		
7.9		1 cycle:		
Temperature		1 step: -40±2°C / 30±3m		
Cycle		2 step: Ordinary temp. / 3m max.		
		3 step: +125±2°C / 30±3m		
		4 step: Ordinary temp. / 3m max.		
		Total of 100 cycles		
		Then measured after exposure Standard atmospheric		
		conditions for 1~2h.		



# 8. Packaging and Marking:





ITEM	W	A0	В0	K0	Р	F	E	D0	P0	P2	Т
DIM	8.00	1.0	1.80	1.10	4.00	3.5	1.75	1.50	4.00	2.00	0.20
TOLE	±0.3	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	+0.1	±0.1	±0.1	±0.05

#### 8-2. Taping Dimensions:



8-3.Reel Dimensions:



Туре	А	В	С	G	Ν	Т
8mm	178	20.7±0.8	13±0.4	9	60	10.8

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8-4. Packaging Quantity:

3KPCS/ Reel

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